

规格书编号

SPEC NO :

产品规格书

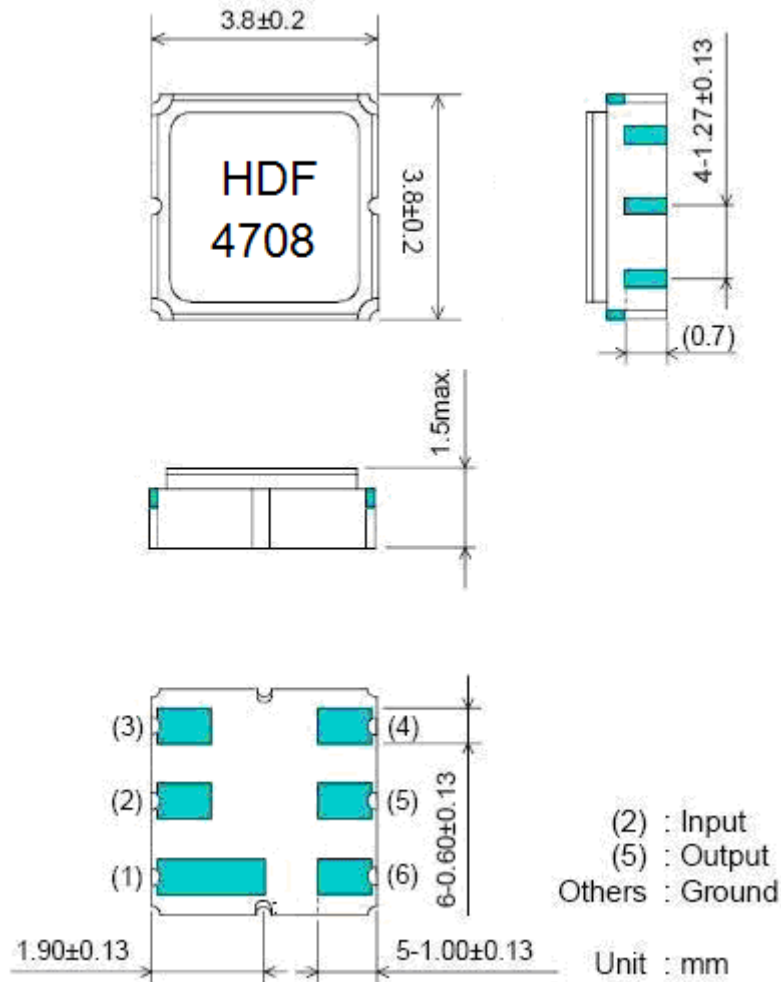
SPECIFICATION

CUSTOMER 客户: _____
PRODUCT 产品: _____ SAW FILTER _____
MODEL NO 型号: _____ HDF770C SMD-4 _____
MARKING 印字: _____ HDF4708 _____
PREPARED 编制: _____ CHECKED 审核: _____
APPROVED 批准: _____ D A T E 日期: _____ 2006-5-11 _____

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. Package Dimension



2. Marking: HDF4708

- HD: Brand
- F : Filter
- 4 : SMD-4
- 708 : No.

3. Performance

3.1 Application

Low-Loss SAW Filter of cordless system.
Center Frequency: 770 MHz

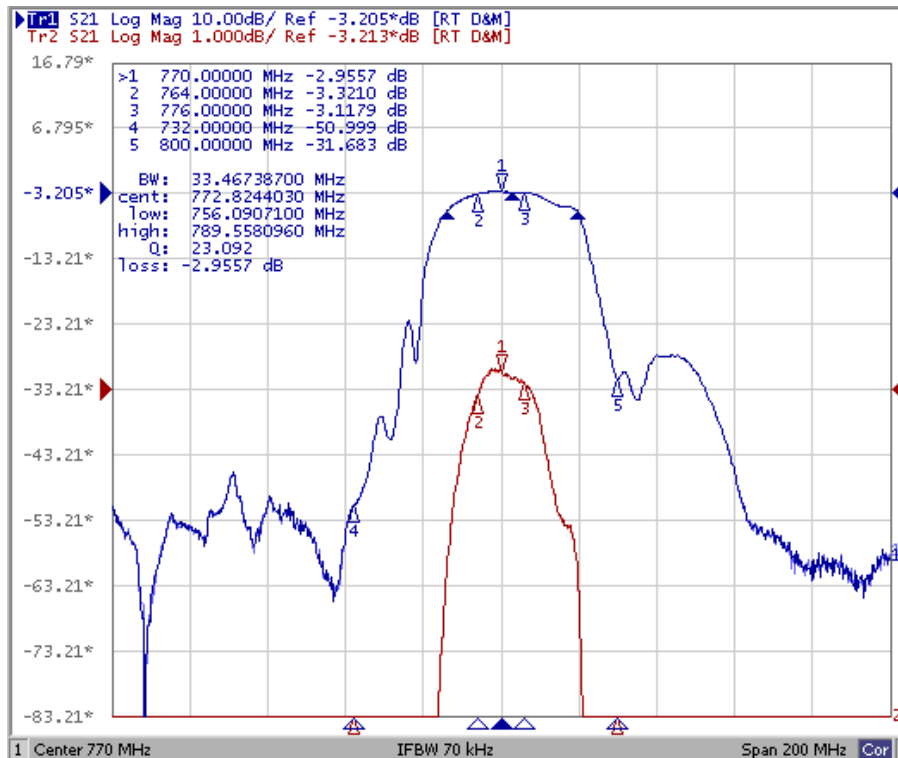
3.2 Maximum Rating

Operation Temperature Range	-40°C to +85°C
Storage Temperature Range	-45°C to +85°C
DC. Permissive Voltage	0 V DC. max.
Maximum Input Power	5dBm

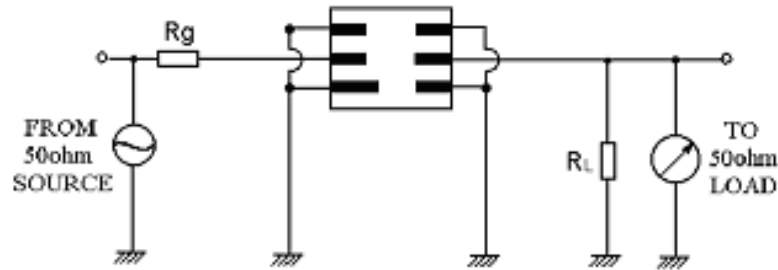
3.3 Electronic Characteristics

Item	Specification
Center Frequency(f_0)	770 MHz
Insertion Loss(dB)	
1.) $f_0 \pm 6.0$ MHz	4.0 dB max
2.) $f_0 - 150 \sim f_0 - 38$ MHz	45 dB min
3.) $f_0 + 30 \sim f_0 + 60$ MHz	20 dB min
4.) $f_0 + 60 \sim f_0 + 150$ MHz	45 dB min
Ripple deviation ($f_0 \pm 6.0$ MHz)(dB)	2.0 max
Input/output Impedance(Nominal)	50 Ω

3.4 Frequency Characteristics



3.5 Test Circuit



4. ENVIRONMENTAL CHARACTERISTICS

4-1 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of $+25^{\circ}\text{C}$ for 5 Minutes and a higher temperature of $+85^{\circ}\text{C}$ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 3.3.

4-2 Resistance to solder heat

Submerge the device terminals into the solder bath at $260^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 3.3.

4-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 3.3.

4-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 3.3.

4-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 3.3.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please

avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

6. Packing

6.1 Dimensions

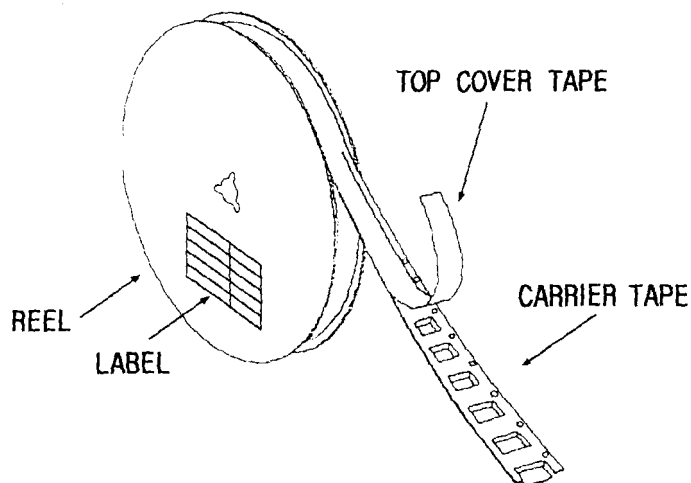
- (1) Carrier Tape: Figure 1
- (2) Reel: Figure 2
- (3) The product shall be packed properly not to be damaged during transportation and storage.

6.2 Reeling Quantity

- 1000 pcs/reel 7''
3000 pcs/reel 13''

6.3 Taping Structure

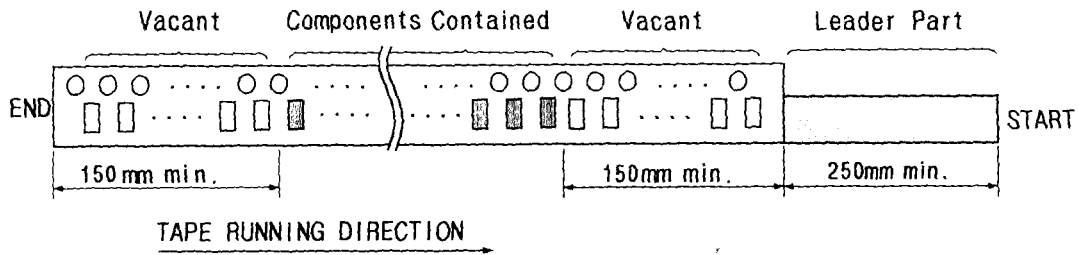
- (1) The tape shall be wound around the reel in the direction shown below.



- (2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

- (3) Leader part and vacant position specifications.

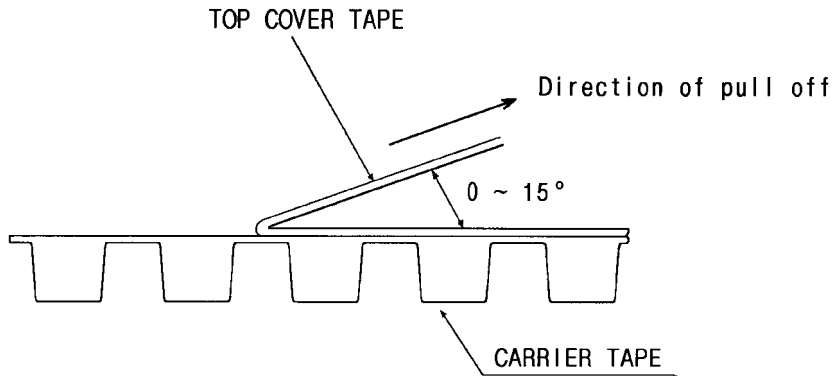


7. TAPE SPECIFICATIONS

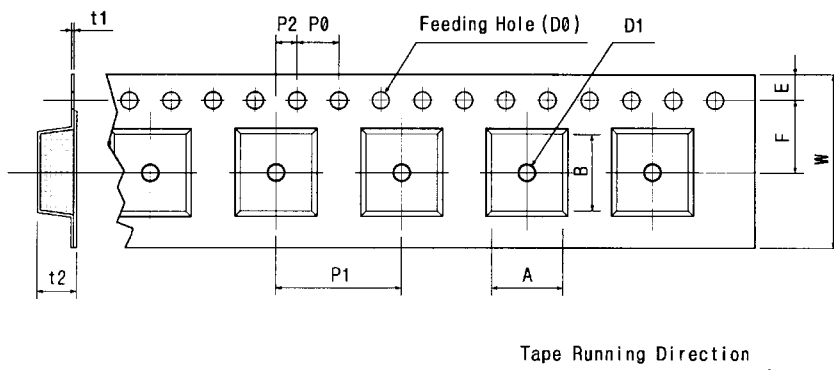
7.1 Tensile Strength of Carrier Tape: 4.4N/mm width

7.2 Top Cover Tape Adhesion (See the below figure)

- (1) pull off angle: 0~15°
- (2) speed: 300mm/min.
- (3) force: 20~70g



[Figure 1] Carrier Tape Dimensions

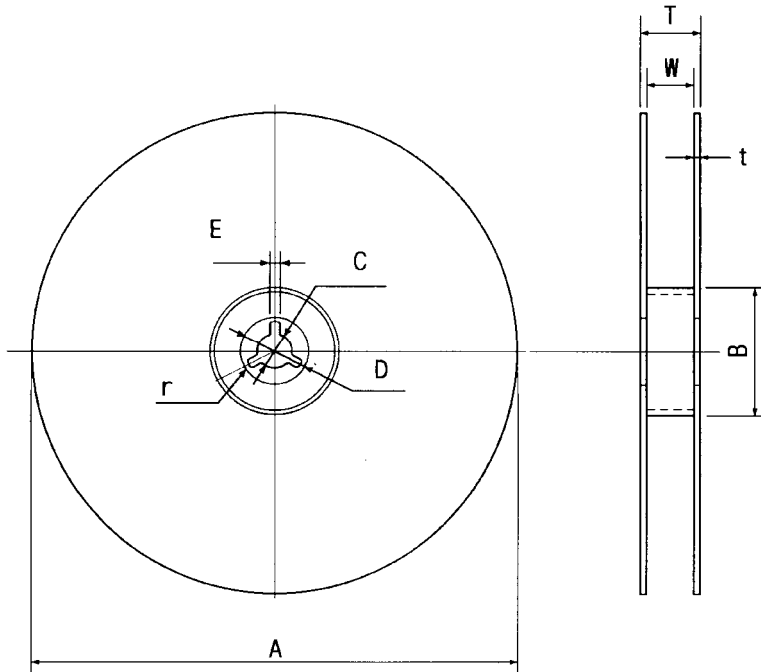


[Unit:mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.00	5.50	1.75	4.00	8.00	2.00	Ø1.50	Ø1.0	0.25	1.65	4.04	4.10
±0.30	±0.10	±0.10	±0.10	±0.10	±0.10		±0.25	±0.05	±0.10	±0.10	±0.10

[Figure 2]

[Unit:mm]



A	B	C	D	E	W	t	r
Ø330	Ø100	Ø13	Ø21	2	13	3	1.0
±1.0	±0.5	±0.5	±0.8	±0.5	±0.3	max.	max.